WAVE FLOW SOLDERING
- GMC SERIES -

FLOW SOLDERING

- Do not apply flow soldering to chips not listed below:

SERIES	CHIP SIZE	TEMPERATURE DIFFERENTIAL
GMC	0201, 0402, 0603, 0805, 1206, 1210, 1808, 1812, 1825, 2220, 2225	ΔT≤150°C

- When sudden heat is applied to the components, the mechanical strength of the components will decrease because a sudden temperature change causes deformation inside the components. In order to prevent mechanical damage to the components, preheating is required for both of the components and the PCB. Preheating conditions are shown in table 2. It is required to keep the temperature differential between the solder and the components surface (ΔT) as low as possible.

- Excessively long soldering time or high soldering temperature can result in leaching of the terminations, causing poor adhesion or a reduction in capacitance value due to loss of contact between the inner electrodes and terminations.

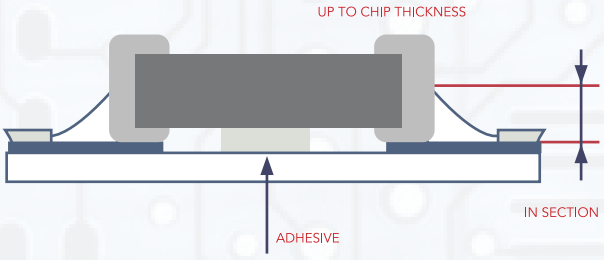
- When components are immersed in solvent after mounting, be sure to maintain the temperature differential (ΔT) between the component and solvent within the range shown in the table above.

RECOMMENDED CONDITIONS	
	LEAD FREE SOLDER
PREHEATING PEAK TEMPERATURE	100 to 120°C
SOLDERING PEAK TEMPERATURE	250 to 260°C
ATMOSPHERE	Air or N_2

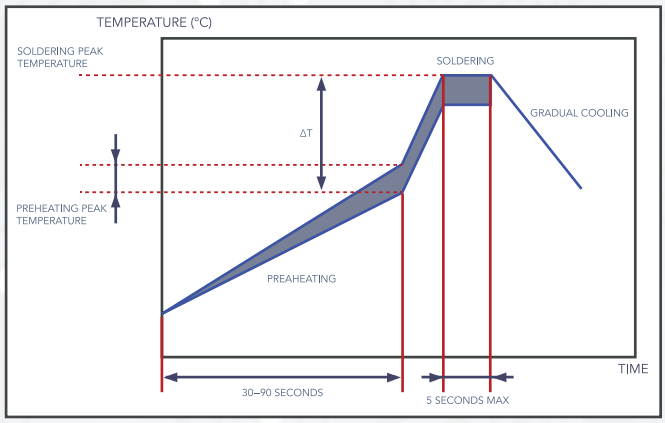
Lead Free Solder: Sn-3.0Ag-0.5Cu

- Optimum Solder Amount for Flow Soldering

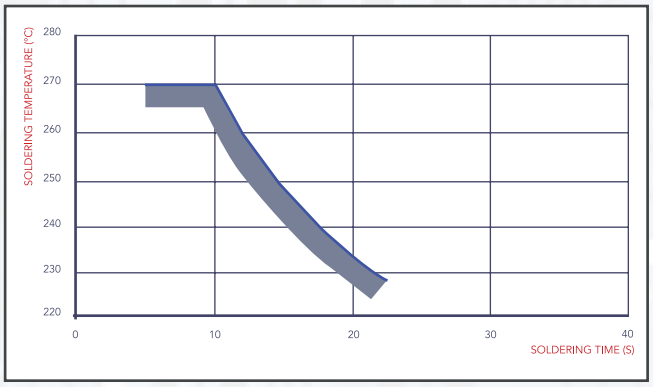
The top of the solder fillet should be lower than the thickness of the components. If the solder amount is excessive, the risk of cracking is higher during board bending or any other stressful condition.



STANDARD CONDITIONS



ALLOWABLE FLOW SOLDERING



- In the case of repeated soldering, the accumulated soldering time must be within the range shown above.

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MS LEVEL 1